

TPA2000D4
Filterless Class-D With
Stereo Headphone
Audio Power Amplifier EVM

User's Guide

Preface

How to Use This Manual

This document contains the following chapters:

- Chapter 1—Introduction
- Chapter 2—Operation

Related Documentation From Texas Instruments

- ***TI Plug-N-Play Audio Amplifier Evaluation Platform*** (literature number SLOU011) provides detailed information on the evaluation platform and its use with TI audio evaluation modules.

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Introduction

This chapter provides an overview of the Texas Instruments (TI) TPA2000D4 filterless class-D audio with stereo headphone amplifier evaluation module (SLOP329). It includes a list of EVM features, a brief illustrated description of the module, and a list of EVM specifications.

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1.1 Feature Highlights

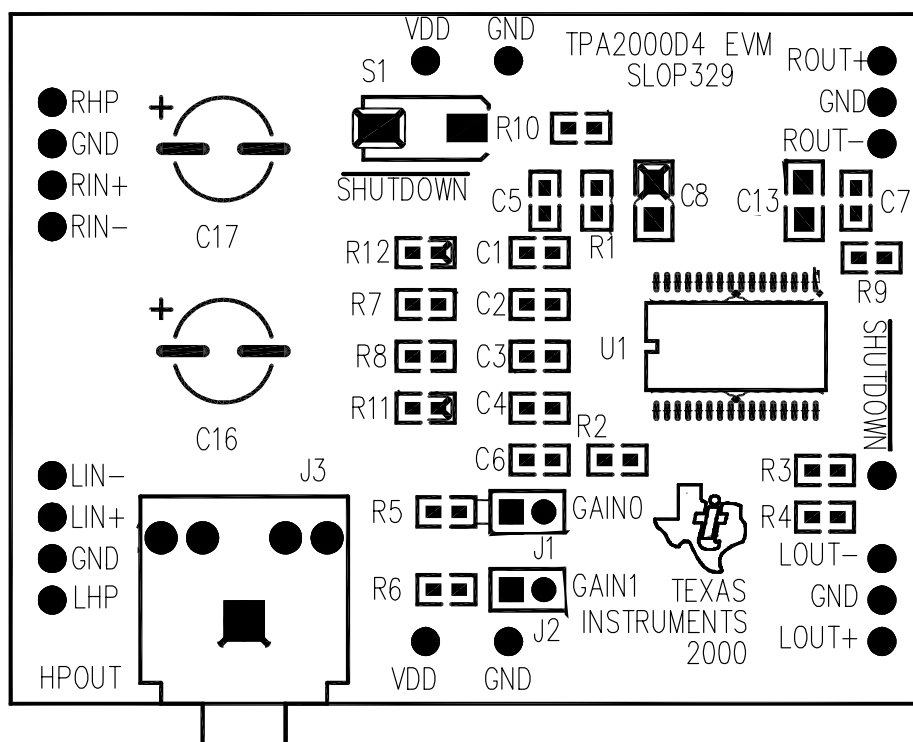
The TI TPA2000D4 audio amplifier evaluation module and the TI plug-n-play audio amplifier evaluation platform include the following features:

- TPA2000D4 Stereo 2-W Filterless Class-D With Stereo Headphone Audio Power Amplifier Evaluation Module
 - Class-D without output filter
 - Stereo headphone output jack
 - Internal depop circuitry to minimize transients in outputs
 - High efficiency
 - Low distortion
 - Low supply current (9 mA for class-D, 7 mA for stereo headphone)
 - 2 W per channel output power into 4 Ω at 5 V
 - Low current consumption in shutdown mode
 - Four selectable gain settings: 5, 11, 17, and 23 dB
 - Differential stereo inputs
 - 32-pin TSSOP PWP package
- Quick and Easy Configuration With the TI Plug-N-Play Audio Amplifier Evaluation Platform
 - Evaluation module is designed to simply plug into the platform, automatically making all signal, control, and power connections
 - Platform provides flexible power options
 - Jumpers on the platform select power and module control options
 - Switches on the platform route signals
 - Platform provides quick and easy audio input and output connections
- Platform Power Options
 - External 5-V – 15-V dc V_{CC} supply inputs
 - External regulated V_{DD} supply input
 - Socket for onboard 5 V/3.3 V V_{DD} voltage regulator EVM
 - Onboard overvoltage and reverse polarity power protection
- Platform Audio Input and Output Connections
 - Left and right RCA phono jack inputs
 - Miniature stereo phone jack input
 - Left and right RCA phono jack outputs
 - Left and right compression speaker terminal outputs
 - Miniature stereo headphone jack output

1.2 Description

The TPA2000D4 filterless class-D stereo audio power amplifier evaluation module is a complete, 2-W per channel class-D stereo audio power amplifier with stereo headphone output jack that can operate without an output filter. It consists of the TI TPA2000D4 class-D stereo 2-W audio power amplifier IC with stereo headphone output jack, along with a small number of other parts mounted on a circuit board that measures approximately 2-1/4 inches by 1-1/2 inches (see Figure 1–1).

Figure 1–1. The TI TPA2000D4 Audio Amplifier EVM—Top View



Single in-line header pins extend from the underside of the module circuit board to allow the EVM to be plugged into the TI plug-n-play audio amplifier evaluation platform, or to be wired directly into existing circuits and equipment when used stand-alone.

The platform has room for a single TPA2000D4 evaluation module and is a convenient vehicle for demonstrating TI's audio power amplifier and related evaluation modules. The EVMs simply plug into the platform, which automatically provides power to the modules, interconnects them correctly, and connects them to a versatile array of standard audio input and output jacks and connectors. Easy-to-use configuration controls allow the platform and EVMs to quickly model many possible end-equipment configurations.

There is nothing to build, nothing to solder, and nothing but the speakers included with the platform to hook up.

1.3 TPA2000D4 EVM Specifications

Supply voltage range, V_{DD}	4.5 V to 5.5 V
Supply current, I_{DD}	2 A max
Continuous output power per channel, BTL, P_O : 4 Ω , $V_{DD} = 5$ V	2 W
Continuous output power per channel, headphones, P_O : 32 Ω , $V_{DD} = 5$ V	85 mW
Minimum load impedance, BTL, R_L	3 Ω
Minimum load impedance, headphone, R_L	16 Ω

Operation

The steps in this chapter can be followed to quickly prepare the TPA2000D4 filterless class-D audio amplifier EVM for use. Using the TPA2000D4 with the TI plug-n-play audio amplifier evaluation platform is a quick and easy way to connect power, signal and control inputs, and signal outputs to the EVM using standard connectors. However, the audio amplifier evaluation module can be used stand-alone by making connections directly to the module pins, and can be wired directly into existing circuits or equipment.

The platform switch and jumper settings shown in Table 2–1 are typical for the TPA2000D4 EVM and will cause the TPA2000D4 to shut down when a plug is inserted into platform headphone jack J10.

Table 2–1. Typical TI Plug-N-Play Platform Jumper and Switch Settings for the TPA2000D4

EVM	JP4	JP5	JP6	JP7	JP8	S2	S3
P-N-P Platform	X	ON	Mute	X	Lo	Note 2	U5

- Notes:**
- 1) ON = Jumper installed, OFF = Jumper **NOT** Installed, X = Don't care
 - 2) Set S2 to ON when signal conditioning board is installed in U1; set S2 to OFF when no signal conditioning board is installed.

Table 2–2. Typical TPA2000D4 EVM Jumper Settings

EVM	GAIN0	GAIN1
TPA2000D4	ON	ON

Note: ON = Jumper installed, OFF = Jumper **NOT** Installed, X = Don't care

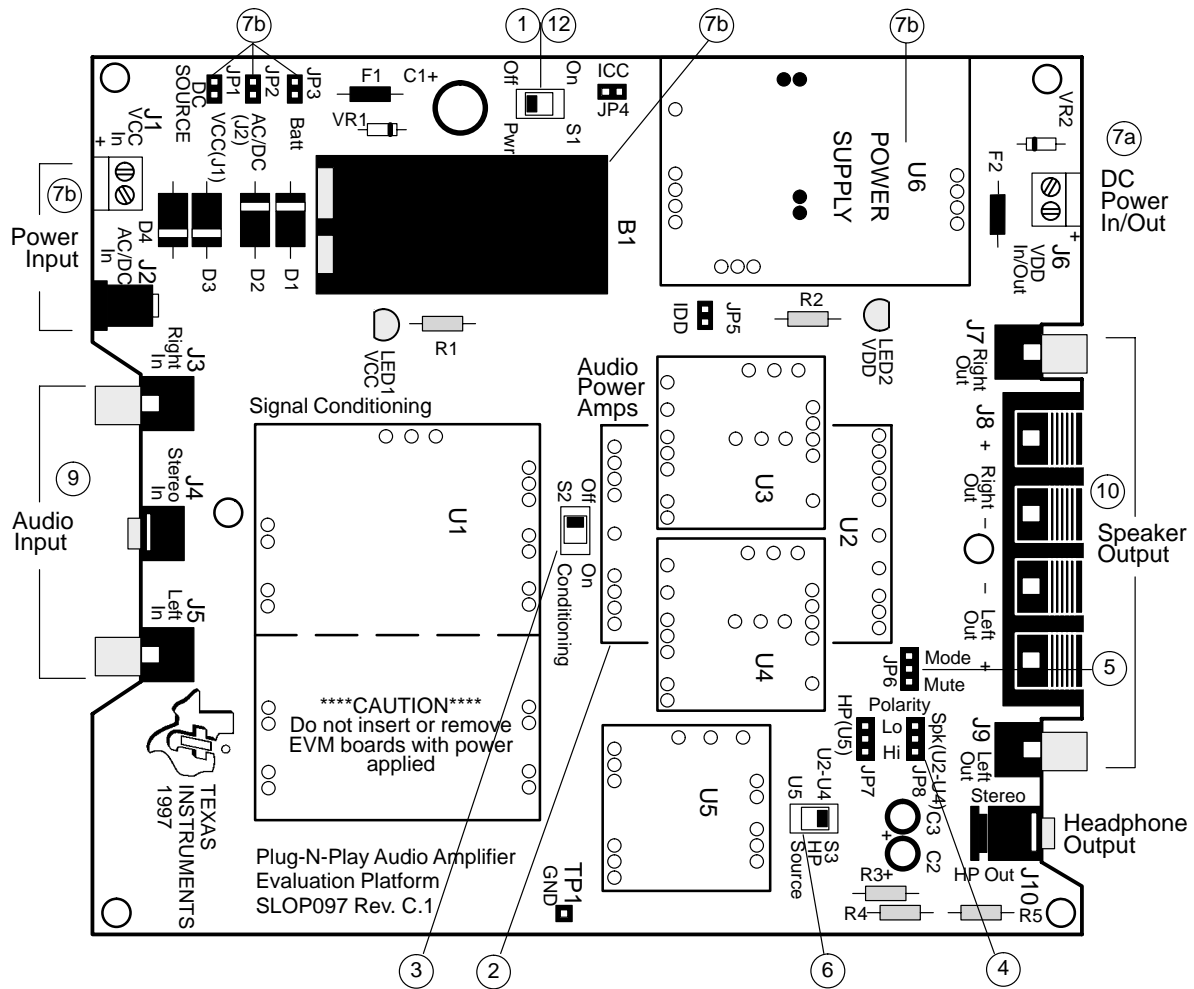
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2.1 Precautions

Power Supply Input Polarity and Maximum Voltage
 Always ensure that the polarity and voltage of the external power connected to V_{CC} power input connector J1, J2, and/or V_{DD} power input connector J6 are correct. Overvoltage or reverse-polarity power applied to these terminals can open onboard soldered-in fuses and cause other damage to the platform, installed evaluation modules, and/or the power source.

Inserting or Removing EVM Boards
 Do not insert or remove EVM boards with power applied—damage to the EVM board, the platform, or both may result.

Figure 2–1. Quick Start Platform Map



2.2 Quick Start List for Platform

Follow these steps when using the TPA2000D4 EVM with the TI plug-n-play audio amplifier evaluation platform (see the platform user's guide, literature number SLOU011, for additional details). Numbered callouts for selected steps are shown in Figure 2–1 and Figure 2–2, and details appear in Chapter 3.

Platform preparations

- 1) Ensure that all external power sources are set to *OFF* and that the platform power switch S1 is set to *OFF*.
- 2) Install a TPA2000D4 module in platform socket U2, taking care to align the module pins correctly.
- 3) Use switch S2 to select or bypass the signal conditioning EVM (U1).
- 4) Set control signal polarity jumper JP8 to *Lo*.
- 5) Set jumper JP6 to select the *Mute* control input (causes the TPA2000D4 to shut down if a plug is inserted into platform headphone jack J10).
- 6) If a headphone amplifier will be installed in U5, set headphone source switch S3 to *U5*.

Table 2–3. Platform Jumper and Switch Settings for the TPA2000D4

EVM	JP4	JP5	JP6	JP7	JP8	S2	S3
P-N-P Platform	X	ON	Mute	X	Lo	Note 2	U5

Notes: 1) ON = Jumper installed, OFF = Jumper *NOT* Installed, X = Don't care
 2) Set S2 to *ON* when signal conditioning board is installed in U1; set S2 to *OFF* when no signal conditioning board is installed.

Power supply

- 7) Select and connect the power supply (ensure power supply is set to *OFF*):
 - a) Connect an external regulated power supply set to 5 V to platform V_{DD} power input connector J6 taking care to observe marked polarity, or
 - b) Install a voltage regulator EVM (SLVP097 or equiv.) in platform socket U6. Connect a 7-V – 12-V power source to a platform V_{CC} power input J1 or J2 and jumper the appropriate power input (see platform user's guide). If using J1, J2, or B1, set S1 to *ON* to supply power to the EVM.

Inputs and outputs

- 8) Ensure that the audio signal source level is set to minimum.
- 9) Connect the audio source to left and right RCA phono jacks J3 and J5 or stereo miniature phone jack J4.
- 10) The outputs are to be configured in the following manner:
 - a) Connect speakers to left and right RCA jacks J7 and J9 or to stripped wire speaker connectors J8.
or
 - b) Insert the headphone into the onboard headphone jack (J3).

Evaluation Module Preparations

- 11) Use jumpers GAIN0 and GAIN1 to set the gain (see Figure 2–2 and Table 2–4).

Figure 2–2. Module Preparation

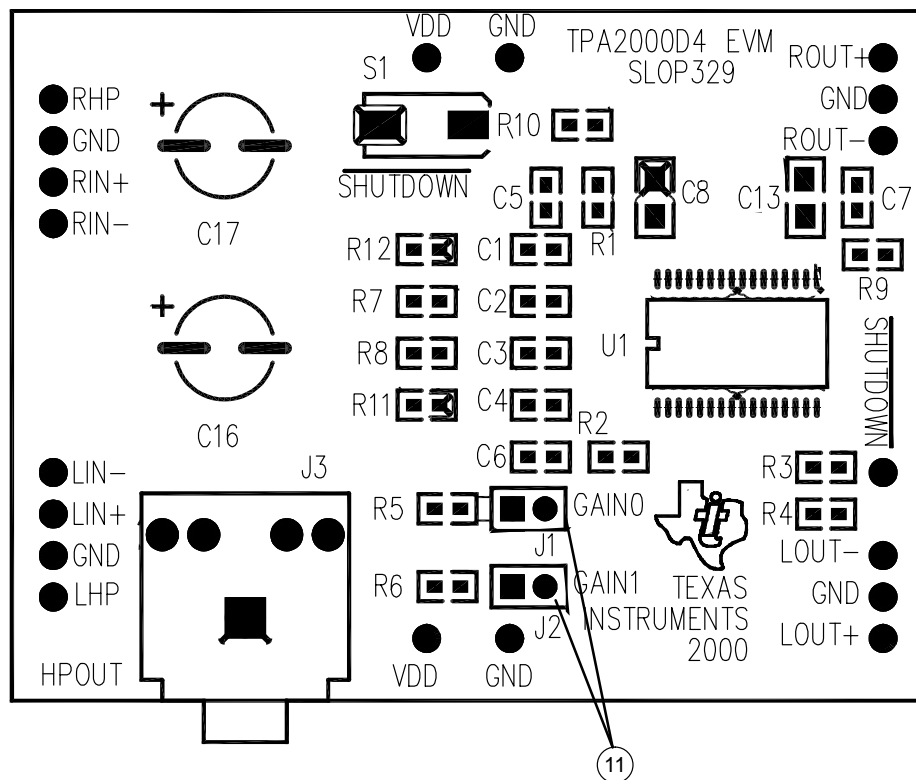


Table 2–4. Typical TPA2000D4 EVM Jumper Settings

GAIN1	GAIN0	GAIN (dB)
ON	ON	5
ON	OFF	11
OFF	ON	17
OFF	OFF	23

Note: ON = Jumper installed, OFF = Open, X = Don't care

Power Up

12) Verify correct voltage and input polarity and set the external power supply to *ON*. If V_{CC} and an onboard regulator EVM are used to provide V_{DD} , set platform power switch S1 to *ON*.

Platform LED2 should light indicating the presence of V_{DD} , and the evaluation modules installed on the platform should begin operation.

13) Adjust the signal source level as needed.

2.3 Quick Start List for Stand-Alone

Follow these steps to use the TPA2000D4 EVM stand-alone or when connecting it into existing circuits or equipment. Connections to the TPA2000D4 module header pins can be made via individual sockets, wire-wrapping, or soldering to the pins, either on the top or the bottom of the module circuit board. Numbered callouts for selected steps are shown in Figure 2–3.

Figure 2–3. Quick Start Module Map



Power supply

- 1) Ensure that all external power sources are set to *OFF*.
- 2) Connect an external regulated power supply set to 5 V to the module VDD and GND pins taking care to observe marked polarity.

Inputs and outputs

- 3) Ensure that audio signal source level adjustments are set to minimum.
- 4) Connect the right (left) positive lead of the audio source to the module RIN+ (LIN+) pins and the negative lead to the RIN- (LIN-) pins.
- 5) The outputs are to be configured in the following manner:
 - a) Connect the speakers to ROUT+ (LOUT+) and ROUT- (LOUT-), making sure that the polarities are observed.
 - or
 - b) Insert the headphone into the onboard headphone jack.

Evaluation module preparations

- 6) Use jumpers GAIN0 and GAIN1 to set the gain as shown in Table 2–5.

Table 2–5. TPA2000D4 EVM Gain Settings

GAIN1	GAIN0	GAIN (dB)
ON	ON	5
ON	OFF	11
OFF	ON	17
OFF	OFF	23

Note: ON = Jumper installed, OFF = Open, X = Don't care

Control inputs

- 7) **SHUTDOWN**: A low shuts down the amplifier IC on the module; a high or float allows normal operation.

Power up

- 8) Connect external power supply set to 5 V across EVM VDD and GND pins.
- 9) Verify correct voltage and input polarity and set the external power supply to ON.

The EVM should begin operation.

- 10) Adjust the signal source level as needed.

2.4 Reference

2.4.1 TPA2000D4 Audio Power Amplifier EVM Parts List

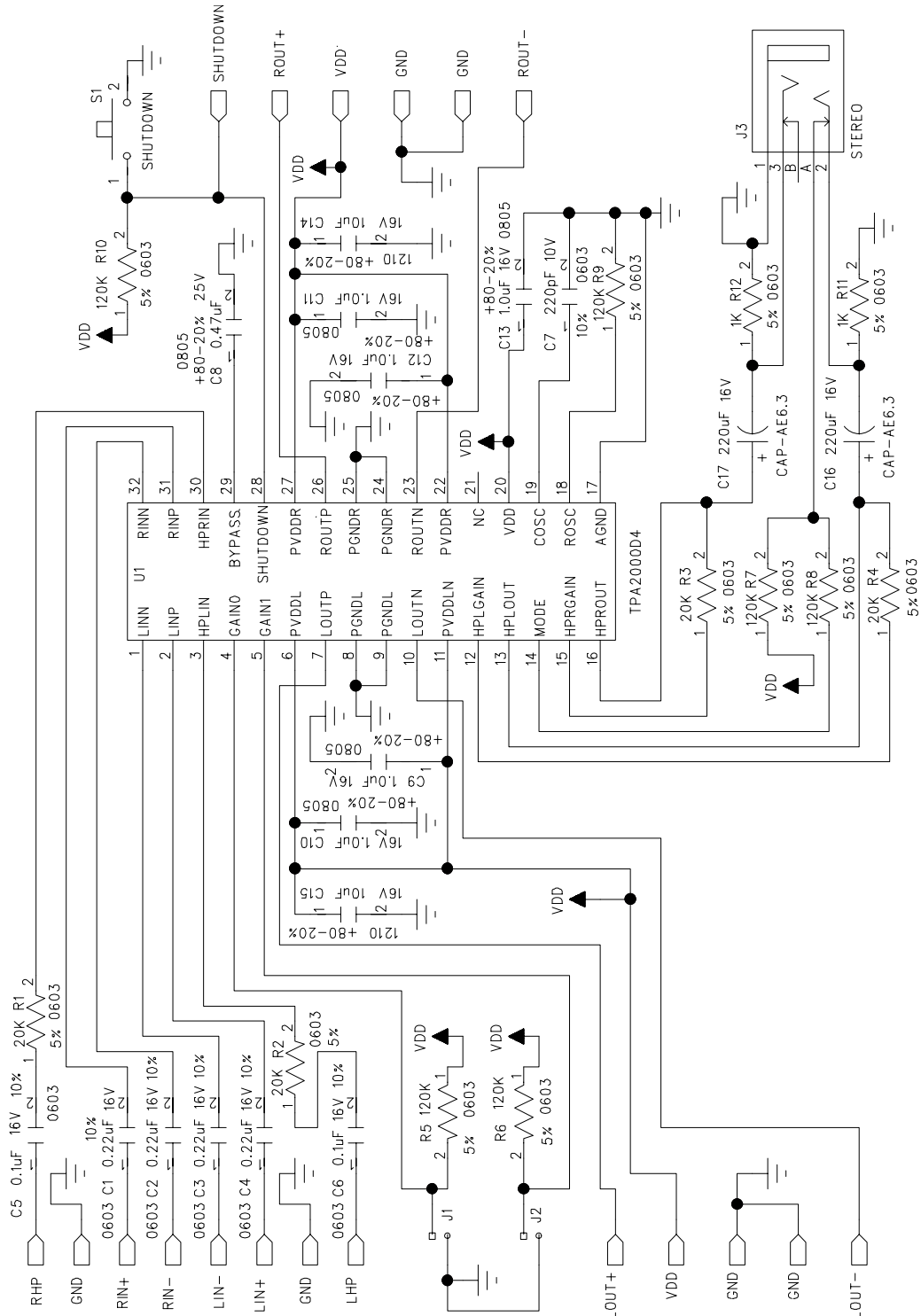
Table 2–6. TPA2000D4 EVM Parts List

Reference	Description	Size	EVM Qty.	Manufacturer/ Part Number
C1–4	Capacitor, ceramic chip, 0.22 μ F, +10%, Y5V, 16 V	0603	4	Murata GRM39–Y5V224Z16
C5, C6	Capacitor, ceramic chip, 0.1 μ F, +10%, X7R, 16 V	0603	2	Murata GRM39–X7R104K16
C7	Capacitor, ceramic, 220 pF, +10%, XICON, 50 V	0603	1	Mouser 140–CC504B221K
C8	Capacitor, ceramic, 0.47 μ F, 80%/–20%, Y5V, 25 V	0805	1	Murata GRM40–Y5V474Z25
C9 – C13	Capacitor, ceramic, 1 μ F, 80%/–20%, Y5V, 16 V	0805	5	Murata GRM40–Y5V105Z16
C14 (Assembled), C15 (Not assembled)	Capacitor, ceramic, 10 μ F, \pm 20%, 16 V		1	Murata GRM235–Y5V106Z016
C16, C17	Capacitor, electrolytic, 220 μ F, 80%/–20%, Y5V, 16 V		2	Nic Components NACE221M16V6.3X8
R1 – R4	Resistor, chip, 20 k Ω , 1/10 W, 5%, XICON	0603	4	Mouser 301–20K
R5 – R10	Resistor, chip, 120 k Ω , 1/10 W, 5%, XICON	0603	5	Mouser 301–120K
R11, R12	Resistor, chip, 1 k Ω , 1/10 W, 5%, XICON	0603	2	Mouser 301–1K
S1 (SHUTDOWN)	Switch, momentary pushbutton, 12 V, 50 mA	0.291 x 0.138 x 0.134"	1	Panasonic EVQ–PJS04K
J1 (GAIN0), J2 (GAIN1)	Header, 2 position shunts	2 mm	2	DigiKey 2163S–02–ND
J3	Stereo headphone jack, 2 switches		1	Mouser 161–3504
PNP Pins	Headers, 0.1 in centers, 1/2 in long	0.5 x 0.25 x 0.1"	19	Samtec T SW–19–8–G–S

2.4.2 TPA2000D4 Filterless Class-D EVM Schematic

The TPA2000D4 filterless class-D EVM schematic is shown in Figure 2–4.

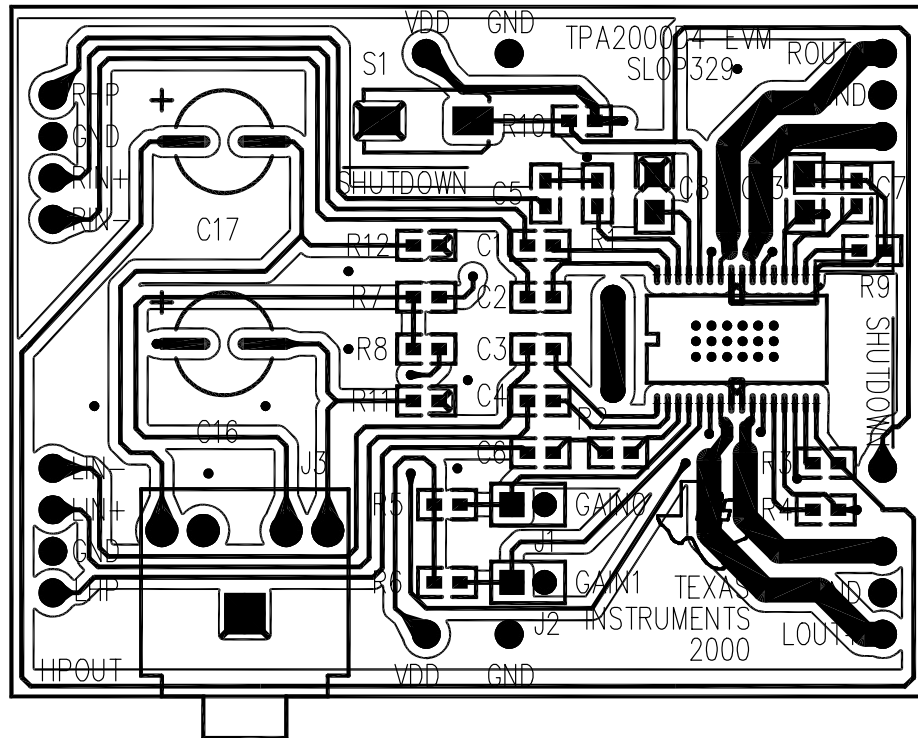
Figure 2–4. TPA2000D4 Class-D EVM Schematic Diagram



2.4.3 TPA2000D4 Filterless Class-D EVM PCB Layers

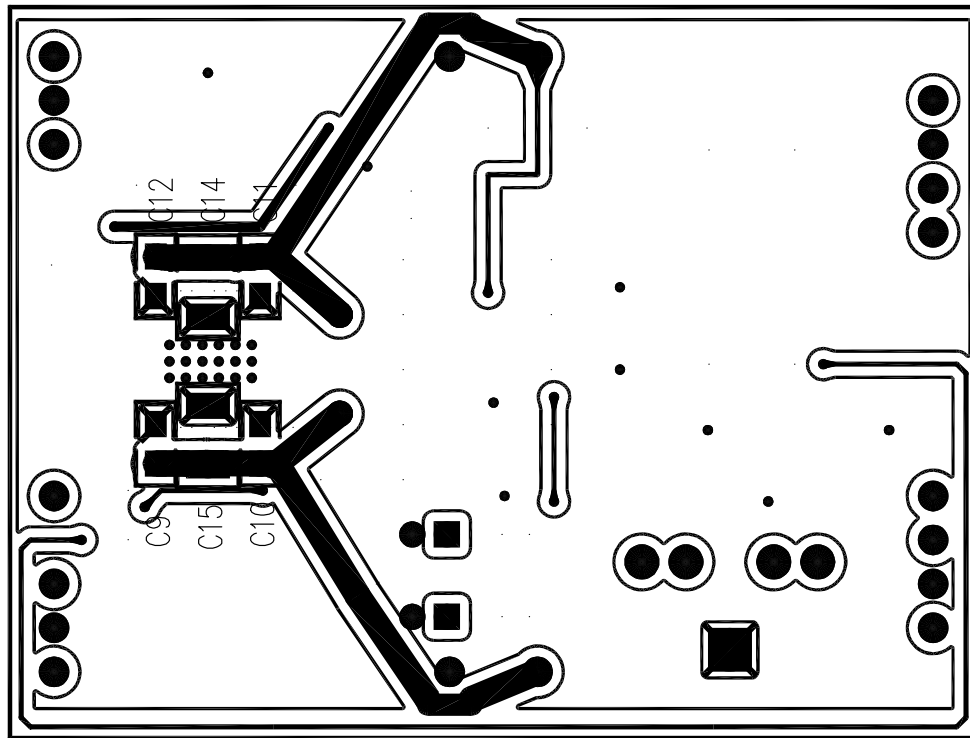
The following illustrations depict the TPA2000D4 filterless class-D EVM PCB assembly and layers. These drawings are not to scale. Gerber plots can be obtained from any TI Sales Office.

Figure 2–5. TPA2000D4 Filterless Class-D EVM Top Assembly



Note: All open areas are solid copper planes.

Figure 2–6. TPA2000D4 Filterless Class-D EVM Bottom Assembly



Note: All open areas are solid copper planes.

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